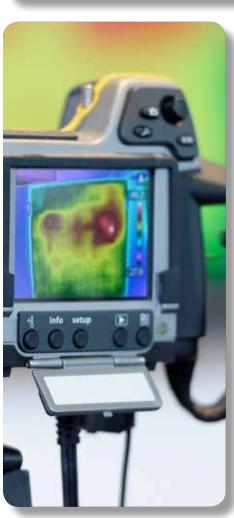
# **92ML**

# Thermally Conductive MultiLayerable Epoxy Laminate and Prepreg



Arlon 92ML ceramic filled thermally conductive multifunctional epoxy laminate and prepreg products provide a cost-effective, lead-free solder compatible, system with enhanced coefficient of thermal conductivity (Tc=2.0 W/m-K) for multilayer PWB applucation that require thermal management throughout the board. 92ML has a UL-94 VO halogen-free flame retardant system that is compliant with ROHS and WEEE and IPC-4101 requirements.



#### Features:

- Thermal Conductivity (Tc) 2.0 W/m-K, 6-8x that of FR-4, reduces hot-spots and dependence on thermal vias and heat-sinks to dissipate heat
- Glass Transition Temperature 160°C provides excellent plated through hole reliability, lead-free solder application
- Decomposition temperature >350°C is ideally suited for lead-free solder processing and offers significant improvement over other thermally conductive laminate materials
- Coefficient of Thermal Expansion close to that of Copper and Aluminum for planar stability during process
- Best-in-class thermal performance with T260 > 60 minutes, T280 > 15 minutes and T300 > 5 minutes.
- Electrical Strength >1000 Volts/mil for use in high power handling Applications
- Engineered for use with metal backing for producing Metal-Clad PCBs
- Meets the flammability requirements of UL-94 V-0
- Halogen-free per IPC-4101 specifications
- ROHS and WEEE compliant

## **Typical Applications:**

- High Brightness LED's
- DC-DC Power Converters
- Automotive Electronics
- Electronic designs with limited thermal management alternatives





# Typical Properties:

| Property                                 | Units             | Value      | Test Method         |
|--|-------------------|------------|---------------------|
| 1. Electrical Properties                 |                   |            |                     |
| Dielectric Constant                      |                   |            |                     |
| @ 1 MHz                                  | -                 | 5.2        | IPC TM-650 2.5.5.3  |
| @ 1 GHz                                  | -                 | 4.9        | IPC TM-650 2.5.5.9  |
| Dissipation Factor                       |                   |            |                     |
| @ 1 MHz                                  | -                 | 0.013      | IPC TM-650 2.5.5.3  |
| @ 1 GHz                                  | -                 |            | IPC TM-650 2.5.5.9  |
| Volume Resistivity                       |                   |            |                     |
| C96/35/90                                | MΩ-cm             | 1.2 x 109  | IPC TM-650 2.5.17.1 |
| E24/125                                  | MΩ-cm             | 1.5 x 109  | IPC TM-650 2.5.17.1 |
| Surface Resistivity                      |                   |            |                     |
| C96/35/90                                | MΩ                | 2.8 x 108  | IPC TM-650 2.5.17.1 |
| E24/125                                  | MΩ                | 4.4 x 108  | IPC TM-650 2.5.17.1 |
| Electrical Strength                      | Volts/mil (kV/mm) | >1000      | IPC TM-650 2.5.6.2  |
| Dielectric Breakdown                     | kV                | >50        | IPC TM-650 2.5.6    |
| Arc Resistance                           | sec               | >150       | IPC TM-650 2.5.1    |
| Dielectric Withstand Voltage (HiPot)     | VDC               | >5000      | IPC TM-650 2.5.7.2  |
| 2. Thermal Properties                    |                   |            |                     |
| Glass Transition Temperature (Tg)        |                   |            |                     |
| DSC                                      | °C                | 160        | IPC TM-650 2.4.25   |
| Decomposition Temperature (Td)           |                   |            |                     |
| Initial                                  | °C                | 340        | IPC TM-650 2.3.41   |
| 5%                                       | °C                | 400        | IPC TM-650 2.3.41   |
| T260                                     | min               | >60        | IPC TM-650 2.4.24.1 |
| T288                                     | min               | >15        | IPC TM-650 2.4.24.1 |
| T300                                     | min               | >5         | IPC TM-650 2.4.24.1 |
| CTE (X,Y)                                | ppm/°C            | 19-20      | IPC TM-650 2.4.41   |
| CTE (Z)                                  |                   |            |                     |
| < Tg                                     | ppm/°C            | 22         | IPC TM-650 2.4.24   |
| > Tg                                     | ppm/°C            | 175        | IPC TM-650 2.4.24   |
| z-axis Expansion (50-260°C)              | %                 | 1.8        | IPC TM-650 2.4.24   |
| 3. Mechanical Properties                 |                   |            |                     |
| Peel Strength to Copper (1 oz/35 micron) |                   | F 0 (0 00) | IDO TIA 050 0 4 0   |
| After Thermal Stress                     | lb/in (N/mm)      | 5.0 (0.88) | IPC TM-650 2.4.8    |
| At Elevated Temperatures                 | lb/in (N/mm)      |            | IPC TM-650 2.4.8.2  |
| After Process Solutions                  | lb/in (N/mm)      | 4.8 (0.84) | IPC TM-650 2.4.8    |
| Young's Modulus                          | Mpsi (GPa)        | 2.6 (18)   | IPC TM-650 2.4.18.3 |
| Flexural Strength                        | kpsi (MPa)        | 26.1 (180) | IPC TM-650 2.4.4    |
| Tensile Strength                         | kpsi (MPa)        | 8.7 (60)   | IPC TM-650 2.4.18.3 |
| Compressive Modulus                      | kpsi (MPa)        |            | ASTM D-695          |
| 4. Physical Properties                   | 0/                | 0.10       | IDO TM 650 0 0 0 4  |
| Water Absorption                         | %                 | 0.12       | IPC TM-650 2.6.2.1  |
| Specific Gravity                         | g/cm3             | 2.2        | ASTM D792 Method A  |
| Thermal Conductivity-Z-Axis              | W/mK              | 2          | ASTM E1461          |
| Thermal Conductivity - X/Y-Axis          | W/mK              | 3.5        | ASTM E1461          |
| Flammability                             | class             | V-0        | UL-94               |

# **Availability:**

| Arlon<br>Part Number | Glass Style |    | Nominal Press<br>Thickness (mils) |            |
|----------------------|-------------|----|-----------------------------------|------------|
| 92ML0488             | 104         | 88 | 3.2                               | Multilayer |
| 92ML0690             | 106         | 90 | 4.2                               | Multilayer |
| 92ML8085             | 1080        | 85 | 6.0                               | Multilayer |

Laminate available in a wide variety of thicknesses with 1/2, 1 or 2 oz copper. Inquire about Aluminum, Copper or Brass plate availability.

## **Recommended Process Conditions:**

Process inner-layers through develop, etch, and strip using standard industry practices. Bake inner layers in a rack for 30 minutes at 107°C - 121°C (225°F - 250°F) immediately prior to lay-up. Vacuum desiccate the prepreg for 8 - 12 hours prior to lamination.

#### Lamination Cycle:

- 1) Control the heat rise to 5°C 7°C (9°F 12°F) per minute between 82°C and 121°C (180°F and 280°F)
- 2) Starting point laminating pressure for 92ML for standard panel sizes are as follows:

| Panel Size |         | Pressure |        |
|------------|---------|----------|--------|
| in         | cm      | psi      | kg/cm² |
| 12 x 18    | 30 x 40 | 250-300  | 17-21  |
| 18 x 24    | 40 x 61 | 300-350  | 21-24  |

- 3) Product temperature at start of cure = 182°C (360°F).
- 4) Cure time at temperature = 90 minutes
- 5) Cool down under pressure at ≤ 5°C/min (10°F/min)

Drill at 350 SFM. Undercut bits are recommended for vias 0.018" and smaller

De-smear using alkaline permanganate or plasma with settings appropriate for multifunctional epoxy.

Conventional plating processes are compatible with 92ML Standard profiling parameters may be used.

Bake for 2 hours at 121°C (250°F) prior to solder reflow or HASL





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For samples, technical assistance, customer service or for more information, please contact Arlon Materials for Electronics Division at the following locations:

#### **NORTH AMERICA:**

Arlon LLC Electronic Substrates 9433 Hyssop Drive

Rancho Cucamonga, CA 91730

Tel: (909) 987-9533 Fax: (909) 987-8541

Arlon LLC

Microwave Materials 1100 Governor Lea Road

Bear, DE 19701 Tel: (800) 635-9333

Outside U.S. & Canada: (302) 834-2100

Fax: (302) 834-2574

#### **NORTHERN EUROPE:**

Arlon LLC 44 Wilby Avenue Little Lever Bolton, Lancashire BL31QE United Kingdom

Tel: (44) 120-457-6068 Fax: (44) 120-479-6463

## **SOUTHERN CHINA:**

Arlon LLC Room 601, Unit 1, Bldg 6 Liyuan, Xincun Shahe Shenzhen, China 518053 Tel: (86) 755-269-066-12 Fax: (86) 755-26910475

#### **NORTHERN CHINA:**

Arlon LLC Room 11/401, No. 8 Hong Gu Road Shanghai, China 200336 Tel/Fax: (86) 21-6209-0202

## **SOUTHERN EUROPE:**

Arlon LLC 6 cours des Juilliottes 94700 Maisons-Alfort France Phone: (33) 1 84 23 41 51 Fax: (33) 9 55 62 43 26